



Christopher Smith
Vice President, New Business Development
(408) 986-9888

Claire McAdams
Investor Relations
(530) 265-9899

**Intevac to Present Fan-Out Packaging Results at IMAPS Device Packaging Conference 2018
*Wins a Best Paper Award from IWLPC 2017***

SANTA CLARA, Calif. — March 1, 2018 – Intevac, Inc. (Nasdaq: IVAC), a leading supplier of thin-film processing systems, today announced its participation in the 14th International Conference and Exhibition on Device Packaging (IMAPS DPC 2018). The company will present its technical paper on “Linear Transport Degas, Pre-Clean, and PVD Processes for RDL Barrier/Seed Formation in Fan-Out Packaging,” at 4:30pm Wednesday afternoon, March 7th, 2018, at the WekoPa Resort in Fountain Hills, Arizona.

Intevac is also pleased to announce recognition by the IWLPC Technical Committee regarding Best Presentation & Papers Awards for IWLPC 2017, based on the combination of technical merit, relevance, originality, knowledge of subject, quality of material, and quality of presentation. Intevac received the Best of Advanced Manufacturing and Test Track Paper Award for its paper on “Process and Productivity Results from a Carrier-Based Linear Transport PVD Systems for RDL Seed Layer Deposition in Fan-Out Packaging Applications.”

For more information visit www.chipscalereview.com/news1801.html#1801-01.

Semiconductor device packaging technology in general, and fan-out wafer-level packaging (FOWLP) / fan-out panel-level packaging (FOPLP) technology in particular, is being driven by the strong cost advantages these advanced packaging technologies offer over the expense of implementing continued Moore's Law progress for sub-10nm semiconductor IC process nodes. Fan-out packaging provides for increased I/O (Input/Output) density for a given semiconductor device while simultaneously supporting smaller packaged die sizes, thereby reducing the amount of space integrated circuit content occupies in handheld consumer electronic products, such as smartphones, wearables, and Internet of Things (IoT) devices.

The INTEVAC MATRIX® is a high-productivity, substrate-independent thin-film processing platform that is well-positioned for multiple fan-out packaging applications. The MATRIX Physical Vapor Deposition (PVD) system offers a much-reduced cost of ownership (COO) over the current PVD process tools being used for Redistribution Layer (RDL) barrier/seed layer applications, and also offers the flexibility to run multiple substrates on the same system, from 300mm wafer-level (round) substrates to panel-level (square or rectangular) substrates, which today are up to 680mm on a side.

About IMAPS DPC 2018

The 14th Annual Device Packaging Conference (DPC 2018) will be held in Fountain Hills, Arizona, on March 5-8, 2018. It is an international event organized by the International Microelectronics Assembly and Packaging Society (IMAPS).

The conference is a major forum for the exchange of knowledge and provides numerous technical, social and networking opportunities for meeting leading experts in these fields. The

conference will attract a diverse group of people within industry and academia. It provides a chance for educational interactions across many different functional groups and experience levels. People who will benefit from this conference include: scientists, process engineers, product engineers, manufacturing engineers, professors, students, business managers, and sales & marketing professionals.

For more information visit www.imaps.org/devicepackaging/.

About IWLPC

IWLPC brings together the semiconductor industry's most respected authorities addressing all aspects of wafer-level, 3D, TSV and integrated system packaging.

Going into its 15th year, the IWLPC is co-produced by Chip Scale Review, the leading international magazine addressing the semiconductor packaging industry, and SMTA, the distinguished global association representing electronic assembly and manufacturing professionals.

The conference comprises three parallel technical tracks with two full days of presentations on wafer-level packaging, 3D integration, and advanced manufacturing and test. Professional development courses, keynote speakers, and panel discussions are offered by world-class experts and enable attendees to broaden their technical knowledge. The technical program includes a two-day expo where 60+ exhibitors showcase their latest technologies and products. The conference provides a collective network of over 800 industry professionals, including vendors from leading semiconductor companies, foundries, and OSATS, as well as key technology, equipment, and materials suppliers in the exhibit area. Attendees will be inspired by the quantity and quality of the featured new developments and emerging technologies. The 15th Annual Conference will be held October 23-25, 2018 in San Jose, CA.

For more information visit: www.iwlpc.com.

About Intevac

Intevac was founded in 1991 and has two businesses: Thin-film Equipment and Photonics.

In our Thin-film Equipment business, we are a leader in the design and development of high-productivity, thin-film processing systems. Our production-proven platforms are designed for high-volume manufacturing of substrates with precise thin film properties, such as the hard drive media, display cover panel, and solar photovoltaic markets we serve currently.

In our Photonics business, we are a recognized leading developer of advanced high-sensitivity digital sensors, cameras and systems that primarily serve the defense industry. We are the provider of integrated digital imaging systems for most U.S. military night vision programs.

For more information call 408-986-9888, or visit the Company's website at www.intevac.com.